Claim Amendments:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method of continuously coating at least one substrate with a buffer layer as a support for a ceramic superconducting material comprising loading the at least one substrate[[s]] onto ~~individual~~ a respective feed spool[[s]], feeding the at least one substrate through a[[n]] vacuum deposition chamber wherein a coating is applied to the at least one substrate while the at least one substrate is ~~being~~ bombarded by ions from dual RF-ion sources, forming at least one coated substrate, and reloading the at least one coated substrate[[s]] onto a respective ~~individual~~ take-up spool[[s]].

2. (Currently Amended) The method of claim 1 where the respective feed spool and take-up spool~~s~~ are located external to the deposition chamber.

3. (Currently Amended) The method of claim 1 where the at least one substrate[[s]] [[are]] is inter-spooled with kapton polymer protective tapes.

4. (Currently Amended) The method of claim 1 where ~~the energy source is a~~ the coating is generated from a deposition source, the deposition source is an ~~a DC~~ electron beam evaporator.

5. (Original) The method of claim 1 where from about 2 to about 12 substrates are simultaneously being coated.

6. (Original) The method of claim 1 where at least two substrates are simultaneously being coated.

7. (Currently Amended) A method of continuously coating at least one substrate with a buffer layer as a support for a ceramic superconducting material comprising:

providing at least one substrate feed spool of substrate,

unspooling and threading the at least one substrate through a vacuum deposition chamber,

loading coating material that is to be deposited onto a surface of the at least one substrate into the vacuum deposition chamber,

reducing the pressure in the deposition chamber to no greater than about 10^{-5} Torr,

injecting oxygen into the deposition chamber,

initializing dual RF-ion sources located in the deposition chamber to a pre-determined power level and trajectory where the resulting ion beams are directed toward the at least one substrate tape[[s]] translating through a deposition zone in the deposition chamber,

eroding the coating material by bombarding the coating material with electrons or ions produced by an energy source selected from the group consisting of DC electron beam, magnetron and ion beam energy sources,

feeding the at least one substrate[[s]] through a deposition zone in the vacuum chamber,

allowing the coating material eroded from the coating source to impinge upon a surface of the at least one substrate[[s]] for a period of time sufficient to deposit a coating of evaporated coating material onto the tape forming at least one coated substrate, and

collecting the at least one coated substrate on ~~individual~~ a respective take-up spool[[s]].

8. (Currently Amended) The method of claim 7 wherein RF ion sources are arranged on opposite sides of the coating source in a manner such that the resulting ion beams are directed toward the at least one substrate ~~tapes~~ at incident angles of approximately 55 degrees.

9. (Currently Amended) A method of continuously coating ~~at least one~~ a plurality of substrates with a buffer layer as a support for a ceramic superconducting material comprising loading the plurality of substrates onto ~~individual~~ respective feed spools, feeding the ~~at least one~~ plurality of substrates through a[[n]] vacuum

deposition chamber wherein a coating is applied to the ~~at least one~~ plurality of substrates in a deposition zone while being bombarded by dual RF-ion sources which ~~impinge~~ are directed at ~~on~~ the plurality of substrates at an incident angle of about 55 degrees and reloading the ~~coated~~ plurality of substrates onto ~~individual~~ respective take-up spools.